

### **AMENDMENTS TO THE CLAIMS**

With this Amendment, claims 1, 3, 15-19, 20, 25 and 26 have been amended and claim 2 has been canceled. This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended)      A heat spreader construction comprising:
  - a base portion having a heat spreading surface comprising a heat-receiving region and a perimeter surface surrounding the heat-receiving region, the base portion comprising a first material selected from the group consisting of copper, copper alloys, aluminum, aluminum alloys, composite carbon-carbon materials, silicon carbide, carbon, graphite, diamond, diamond composite materials and combinations thereof; and
  - a frame portion comprising a second material and interfacing the perimeter surface, the frame portion having a thickness and having an opening traversing the thickness, the second material comprising at least one member selected from the group consisting of copper, copper alloys, aluminum, aluminum alloys, composite carbon materials, diamond, diamond composites, ceramic materials, molybdenum, tungsten, KOVAR® nickel-cobalt iron, nickel-iron, silicon carbide, carbon, graphite, [[ and]] heat-stable polymer materials and combinations thereof, and wherein the second material is a different material than the first material.
2. (Canceled)
3. (Currently Amended)      A heat spreader construction comprising:
  - a base portion having a heat spreading surface comprising a heat-receiving region and a perimeter surface surrounding the heat-receiving region, the base portion comprising a first material selected from the group consisting of copper, copper alloys, aluminum, aluminum alloys, composite carbon-carbon materials, silicon carbide, carbon, graphite, diamond, diamond composite materials, and combinations thereof;
  - a metallic coating over at least a portion of the heat spreading surface; and

a frame portion comprising a second material and interfacing the perimeter surface, the frame portion having a thickness and having an opening traversing the thickness, the second material comprising at least one member of the group consisting of copper, copper alloys, aluminum, aluminum alloys, composite carbon materials, diamond, diamond composites, ceramic materials, molybdenum, tungsten, ~~KOVAR®~~ nickel-cobalt iron, nickel-iron, silicon carbide, carbon, graphite, [[and]] heat-stable polymer materials and combinations thereof;  
wherein the second material is a different material than the first material.

4. (Original) The heat spreader construction of claim 1 further comprising an interface material disposed between the frame portion and the base portion.
5. (Original) The heat spreader construction of claim 4 wherein the interface material comprises a member of the group consisting of an adhesive material and a solder material.
6. (Original) The heat spreader construction of claim 1 wherein the first material has a thermal conductivity of greater than 300 W/mk.
7. (Original) The heat spreader construction of claim 1 wherein the first material has a thermal conductivity of greater than 400 W/mk.
8. (Original) The heat spreader construction of claim 1 wherein the first material has a coefficient of thermal expansion of less than 9 ppm/K.
9. (Original) The heat spreader construction of claim 1 wherein the first material has a coefficient of thermal expansion of less than 6 ppm/K.
10. (Original) The heat spreader construction of claim 1 wherein the frame portion is in direct physical contact with the base portion.

11. (Original) The heat spreader construction of claim 10 wherein the base portion and the frame portion are joined by a diffusion bond.

12. (Original) The heat spreader construction of claim 1 further comprising a coating material over at least a portion of the heat spreading surface.

13. (Original) The heat spreader construction of claim 1 further comprising a coating material over at least a portion of the perimeter surface.

14. (Original) The heat spreader construction of claim 13 wherein the coating material is a metallic material.

15. (Currently Amended) A method of forming a heat spreader construction, comprising:  
forming a base portion comprising a first material and having a first surface comprising a perimeter region surrounding a heat-receiving surface, wherein the first material is selected from the group consisting of copper, copper alloys, aluminum, aluminum alloys, composite carbon-carbon materials, silicon carbide, carbon, graphite, diamond, diamond composite materials, and combinations thereof;  
forming a frame portion comprising a second material, wherein the second material comprises at least one member of the group consisting of copper, copper alloys, aluminum, aluminum alloys, composite carbon materials, diamond, diamond composites, ceramic materials, molybdenum, tungsten, nickel-cobalt iron, nickel-iron, silicon carbide, carbon, graphite, heat-stable polymer materials and combinations thereof, and wherein the second material is a different material than the first material; and  
joining the base portion and the frame portion to form an independent heat spreader construction for subsequent incorporation into an integrated circuitry construction[[s]].

16. (Currently Amended) The method of claim 15 wherein[[ the]] joining the base portion and the frame portion comprises attaching the frame portion and the perimeter region,[[ the]] and

wherein attaching the frame portion and the perimeter portion comprises ~~comprising~~ at least one of soldering, diffusion bonding and application of an adhesive material.

17. (Currently Amended) The ~~heat spreader construction method~~ method of claim 15 wherein the first material comprises ~~at least one member of the group consisting of copper, copper alloys, aluminum, aluminum alloys, composite carbon-carbon materials, or [[and ]]diamond~~ composite materials.

18. (Currently Amended) The ~~heat spreader construction method~~ method of claim 15 wherein the second material comprises ~~at least one member of the group consisting of copper, copper alloys, aluminum, aluminum alloys, composite carbon-carbon materials and diamond~~ or silicon carbide.

19. (Currently Amended) The method of claim 15 further comprising applying a metallic coating material over at least a portion of the first surface prior to ~~[[ the]]~~ joining the base portion and the frame portion.

20. (Currently Amended) Integrated circuitry comprising:  
a heat-generating device; and  
a heat spreader construction in thermal communication with the heat-generating device,  
the heat spreader construction comprising:  
a base portion having a heat spreading surface disposed in heat-receiving relation relative to the heat-generating device, the base portion having a perimeter surface surrounding the heat spreading surface, the base portion comprising at least one material selected from the group consisting of copper, copper alloys, aluminum, aluminum alloys, composite carbon-carbon materials, silicon carbide, carbon, graphite, diamond, diamond composite materials, and combinations thereof; and  
a frame portion interfacing the perimeter surface, the frame portion having a thickness and having an opening traversing the thickness, the frame portion comprising at least one material selected from the group consisting of copper, copper alloys, aluminum, aluminum alloys, composite carbon

materials, diamond, diamond compositions, ceramic materials, molybdenum, tungsten, ~~KOVAR®~~ nickel-cobalt iron, nickel-iron, silicon carbide, carbon, graphite,[[ and]] heat-stable polymer materials and combinations thereof;

wherein the material of the frame portion is a different material than the material of the base portion.

21. (Original) The integrated circuitry of claim 20 wherein the heat-generating device is a flip-chip.
22. (Original) The integrated circuitry of claim 20 further comprising a circuitry board, wherein the heat spreader is mounted to the circuitry board with an interface material comprising at least one of an adhesive and a solder.
23. (Original) The integrated circuitry of claim 20 further comprising an interface material disposed between the heat-generating device and the heat spreading surface.
24. (Original) The integrated circuitry of claim 20 further comprising a heat-sink in thermal communication with the heat spreader.
25. (Currently Amended) A method of forming integrated circuitry comprising:  
providing an integrated circuitry board having a heat-generating device mounted thereon;  
after providing the integrated circuitry board, mounting an independently formed heat spreader in thermal communication with the heat-generating device, the heat spreader comprising:  
a base portion comprising a first material, the base portion having a heat-receiving surface and a perimeter region around the heat-receiving surface, wherein the first material is selected from the group consisting of copper, copper alloys, aluminum, aluminum alloys, composite carbon-carbon materials, silicon carbide, carbon,

graphite, diamond, diamond composite materials, and combinations thereof; and

a frame portion comprising a second material interfacing the perimeter region, wherein the second material comprises at least one member of the group consisting of copper, copper alloys, aluminum, aluminum alloys, composite carbon materials, diamond, diamond composites, ceramic materials, molybdenum, tungsten, nickel-cobalt iron, nickel-iron, silicon carbide, carbon, graphite, heat-stable polymer materials and combinations thereof;  
wherein the second material is a different material than the first material.

26. (Currently Amended) The method of claim 25 further comprising mounting the heat[[-]]spreader to the circuitry board utilizing at least one of an adhesive and a solder.

27. (Original) The method of claim 25 wherein the heat-generating device is a flip-chip.

28. (Original) The method of claim 25 further comprising providing a thermal interface material between the heat-generating device and the heat-receiving surface, the thermal interface material being selected from the group consisting of thermal grease, metallic thermal interface materials, phase-change materials, thermal gels, and indium alloys.